

## Application Data Sheet

### **Application Information**

Application Type:: Regular  
Subject Matter:: Utility  
Title:: Composite Lid For Land Grid Array  
(LGA) Flip-Chip Package Assembly  
Attorney Docket Number:: TI-35061 (1962-07300)  
Request for Early Publication?:: No  
Request for Non-Publication?:: No  
Suggested Drawing Figure:: 1  
Total Drawing Sheets:: 4  
Small Entity?:: No

### **Applicant Information**

Applicant Authority type:: Inventor  
Primary Citizenship Country:: Taiwan  
Status:: Full Capacity  
Given Name:: Tz-Cheng  
Family Name:: CHIU  
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State or Province of Residence:: TX  
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### **Correspondence Information**

Correspondence Customer Number:: 23494

**Representative Information**

Representative Customer Number:: 23494

**Assignee Information**

Assignee name:: Texas Instruments Incorporated  
Street of mailing address:: P.O. Box 655474, MS 3999  
City of mailing address:: Dallas  
State or Province of  
mailing address:: TX  
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